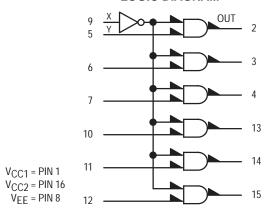
Hex Buffer With Enable

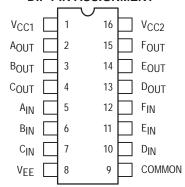
The MC10188 is a high–speed hex buffer with a common Enable input. When Enable is in the high state, all outputs are in the low state. When Enable is in the low state, the outputs take the same state as the inputs.

- Power Dissipation = 180 mW typ/pkg (No Load)
- Propagation Delay = 2.0 ns typ (B Q)
 2.5 ns typ (A Q)

LOGIC DIAGRAM



DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

TRUTH TABLE

Inp	uts	Output		
Х	Υ	OUT		
L	L	L		
L	Н	Н		
Н	L	L		
Н	Н	L		



ON Semiconductor

http://onsemi.com

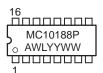
MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620 MC10188L AWLYYWW



PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10188L	CDIP-16	25 Units / Rail
MC10188P	PDIP-16	25 Units / Rail
MC10188FN	PLCC-20	46 Units / Rail

MC10188

ELECTRICAL CHARACTERISTICS

				Test Limits						
			Pin Under	-30)∘C	+2	5°C	+8	5°C	ĺ
Characteristic		Symbol Test		Min	Max	Min	Max	Min	Max	Unit
Power Supply Drain Co	urrent	ΙΕ	8		46		42		46	mAdc
Input Current		linH	5		425		265		265	μAdc
		linH	9		460		290		290	μAdc
Output Voltage	Logic 1	Vон	2	-1.060	-0.890	-0.960	-0.810	-0.890	-0.700	Vdc
Output Voltage	Logic 0	VOL	2	-1.890	-1.675	-1.850	-1.650	-1.825	-1.615	Vdc
Threshold Voltage	Logic 1	Vона	2	-1.080		-0.980		-0.910		Vdc
Threshold Voltage	Logic 0	VOLA	2		-1.655		-1.630		-1.595	Vdc
Switching Times	(50Ω Load)									ns
Propagation Delay	Enable Data	^t PHL ^t PLH	2 2	1.1 1.0	3.9 3.3	1.1 1.0	3.5 2.9	1.1 1.0	3.9 3.3	
Rise/Fall Time	(20 to 80%)	tTLH tTHL	2	1.1	3.7	1.1	3.3	1.1	3.7	

ELECTRICAL CHARACTERISTICS (continued)

				TEST VOLTAGE VALUES (Volts)					
@ Test Temperature			V _{IHmax}	V _{ILmin}	VIHAmin	V _{ILAmax}	VEE		
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
Pin				TEST V	OLTAGE AP	PLIED TO P	INS LISTED I	BELOW	()/)
Characteristic		Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(VCC) Gnd
Power Supply Drain C	ΙE	8					8	1, 16	
Input Current		linH	5	5				8	1, 16
		linH	9	9				8	1, 16
Output Voltage	Logic 1	Voн	2	5				8	1, 16
Output Voltage	Logic 0	VOL	2		9			8	1, 16
Threshold Voltage	Logic 1	Vона	2			5		8	1, 16
Threshold Voltage	Logic 0	VOLA	2				5	8	1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	−3.2 V	+2.0 V
Propagation Delay	Enable Data	^t PHL ^t PLH	2 2			9 5	2 2	8 8	1, 16 1, 16
Rise/Fall Time	(20 to 80%)	tTLH tTHL	2			5	2	8	1, 16

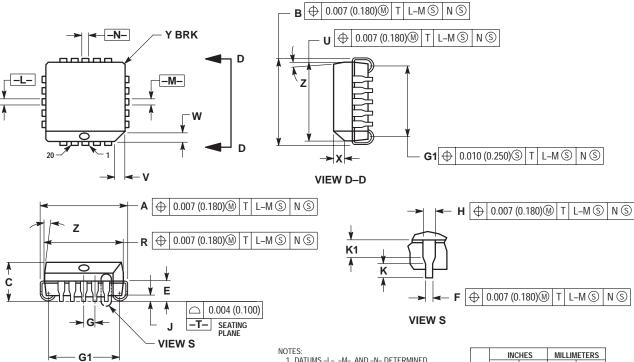
Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

MC10188

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 **ISSUE C**



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

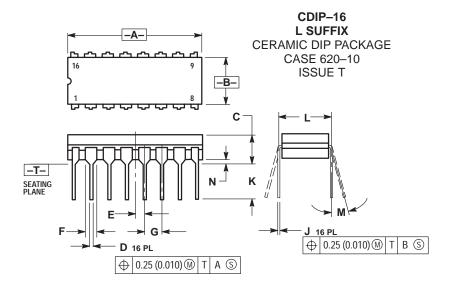
- DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTRA FRAST BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	IETERS		
DIM	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

MC10188

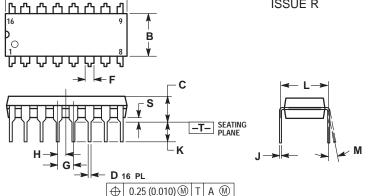


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN
- FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC	
M	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIMETERS			
DIM	MIN MAX		MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015 0.021		0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54 BSC			
Н	0.050	BSC	1.27 BSC			
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295 0.305		7.50	7.74		
M	0°	0° 10°		10 °		
S	0.020 0.040		0.51	1.01		

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